



November 2002

ADC08200

8-Bit, 20 MSPS to 200 MSPS, 1.05 mW/MSPS A/D Converter

General Description

The ADC08200 is a low-power, 8-bit, monolithic analog-to-digital converter with an on-chip track-and-hold circuit. Optimized for low cost, low power, small size and ease of use, this product operates at conversion rates up to 230 MSPS while consuming just 1.05 mW per MHz of clock frequency, or 210 mW at 200 MSPS. Raising the PD pin puts the ADC08200 into a Power Down mode where it consumes 1 mW.

The unique architecture achieves 7.3 Effective Bits with 50 MHz input frequency. The ADC08200 is resistant to latch-up and the outputs are short-circuit proof. The top and bottom of the ADC08200's reference ladder are available for connections, enabling a wide range of input possibilities. The digital outputs are TTL/CMOS compatible with a separate output power supply pin to support interfacing with 3V or 2.5V logic. The digital inputs (CLK and PD) are TTL/CMOS compatible.

The ADC08200 is offered in a 24-lead plastic package (TSSOP) and is specified over the industrial temperature range of -40°C to +85°C.

Features

- Single-ended input
- Internal sample-and-hold function
- Low voltage (single +3V) operation
- Small package
- Power-down feature

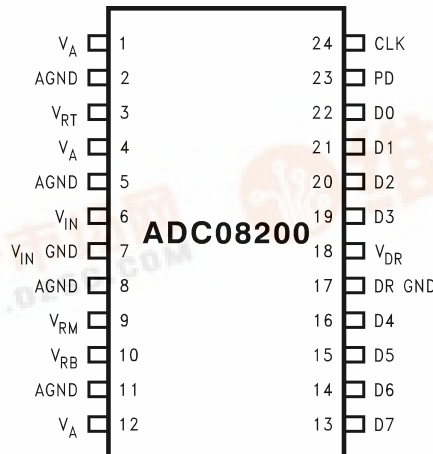
Key Specifications

■ Resolution:	8 bits
■ Maximum sampling frequency:	200 MSPS (min)
■ DNL:	±0.4 LSB (typ)
■ ENOB ($f_{IN}= 50$ MHz):	7.3 bits (typ)
■ THD ($f_{IN}= 50$ MHz):	-61 dB (typ)
■ No missing codes	Guaranteed
■ Power Consumption	
Operating	1.05 mW/MSPS (typ)
Power down	1 mW (typ)

Applications

- Flat panel displays
- Projection systems
- Set-top boxes
- Battery-powered instruments
- Communications
- Medical scan converters
- X-ray imaging
- High speed viterbi decoders
- Astronomy

Pin Configuration



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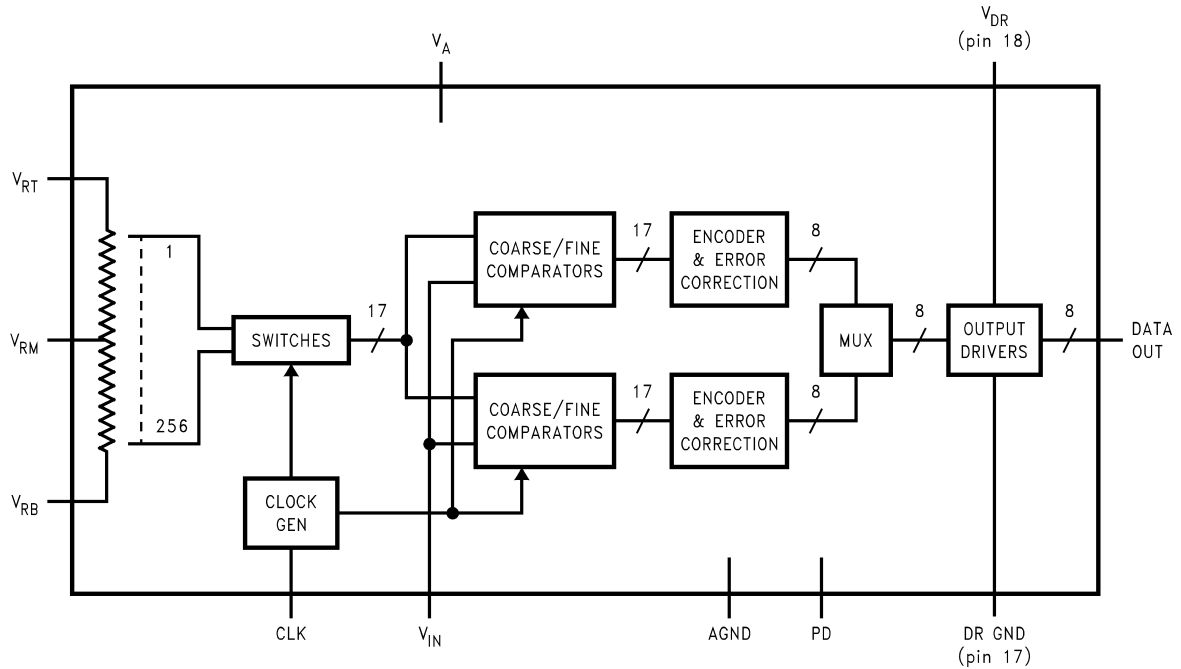
ADC08200 8-Bit, 20 MSPS to 200 MSPS, 1.05 mW/MSPS A/D Converter



Ordering Information

ADC08200CIMT	TSSOP
ADC08200CIMTX	TSSOP (tape and reel)

Block Diagram



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Pin Descriptions and Equivalent Circuits

Pin No.	Symbol	Equivalent Circuit	Description
6	V_{IN}		Analog signal input. Conversion range is V_{RB} to V_{RT} .
3	V_{RT}		Analog Input that is the high (top) side of the reference ladder of the ADC. Nominal range is 0.5V to V_A . Voltage on V_{RT} and V_{RB} inputs define the V_{IN} conversion range. Bypass well. See Section 2.0 for more information.
9	V_{RM}		Mid-point of the reference ladder. This pin should be bypassed to a quiet point in the analog ground plane with a 0.1 μ F capacitor.
10	V_{RB}		Analog Input that is the low side (bottom) of the reference ladder of the ADC. Nominal range is 0.0V to ($V_{RT} - 0.5V$). Voltage on V_{RT} and V_{RB} inputs define the V_{IN} conversion range. Bypass well. See Section 2.0 for more information.

Pin Descriptions and Equivalent Circuits (Continued)

Pin No.	Symbol	Equivalent Circuit	Description
23	PD		Power Down input. When this pin is high, the converter is in the Power Down mode and the data output pins hold the last conversion result.
24	CLK		CMOS/TTL compatible digital clock Input. V_{IN} is sampled on the rising edge of CLK input.
13 thru 16 and 19 thru 22	D0–D7		Conversion data digital Output pins. D0 is the LSB, D7 is the MSB. Valid data is output just after the rising edge of the CLK input.
7	V_{IN} GND		Reference ground for the single-ended analog input, V_{IN} .
1, 4, 12	V_A		Positive analog supply pin. Connect to a quiet voltage source of +3V. V_A should be bypassed with a 0.1 μ F ceramic chip capacitor for each pin, plus one 10 μ F capacitor. See Section 3.0 for more information.
18	V_{DR}		Power supply for the output drivers. If connected to V_A , decouple well from V_A .
17	DR GND		The ground return for the output driver supply.
2, 5, 8, 11	AGND		The ground return for the analog supply.

Absolute Maximum Ratings (Notes 1, 2)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Supply Voltage (V_A)	3.8V
Driver Supply Voltage (V_{DR})	$V_A + 0.3V$
Voltage on Any Input or Output Pin	-0.3V to V_A
Reference Voltage (V_{RT} , V_{RB})	V_A to AGND
CLK, PD Voltage Range	-0.05V to ($V_A + 0.05V$)
Input Current at Any Pin (Note 3)	± 25 mA
Package Input Current (Note 3)	± 50 mA
Power Dissipation at $T_A = 25^\circ\text{C}$	See (Note 4)
ESD Susceptibility (Note 5)	
Human Body Model	2500V
Machine Model	200V

Soldering Temperature, Infrared,	235°C
10 seconds (Note 6)	
Storage Temperature	-65°C to +150°C

Operating Ratings (Notes 1, 2)

Operating Temperature Range	$-40^\circ\text{C} \leq T_A \leq +85^\circ\text{C}$
Supply Voltage (V_A)	+2.7V to +3.6V
Driver Supply Voltage (V_{DR})	+2.4V to V_A
Ground Difference IGND - DR GNDI	0V to 300 mV
Upper Reference Voltage (V_{RT})	0.5V to ($V_A - 0.3V$)
Lower Reference Voltage (V_{RB})	0V to ($V_{RT} - 0.5V$)
V_{IN} Voltage Range	V_{RB} to V_{RT}

Converter Electrical Characteristics

The following specifications apply for $V_A = V_{DR} = +3.0V_{DC}$, $V_{RT} = +1.9V$, $V_{RB} = 0.3V$, $C_L = 5$ pF, $f_{CLK} = 200$ MHz at 50% duty cycle. **Boldface limits apply for $T_A = T_{MIN}$ to T_{MAX}** ; all other limits $T_A = 25^\circ\text{C}$ (Notes 7, 8)

Symbol	Parameter	Conditions	Typical (Note 9)	Limits (Note 9)	Units (Limits)
DC ACCURACY					
INL	Integral Non-Linearity		+1.0 -0.3	+1.9 -1.2	LSB (max) LSB (min)
DNL	Differential Non-Linearity		± 0.4	± 0.95	LSB (max)
	Missing Codes			0	(max)
FSE	Full Scale Error		36	50	mV (max)
V_{OFF}	Zero Scale Offset Error		46	60	mV (max)
ANALOG INPUT AND REFERENCE CHARACTERISTICS					
V_{IN}	Input Voltage		1.6	V_{RB}	V (min)
				V_{RT}	V (max)
C_{IN}	V_{IN} Input Capacitance	$V_{IN} = 0.75V + 0.5$ V_{rms}	(CLK LOW)	3	pF
			(CLK HIGH)	4	pF
R_{IN}	R_{IN} Input Resistance		>1		M Ω
BW	Full Power Bandwidth		500		MHz
V_{RT}	Top Reference Voltage		1.9	V_A	V (max)
				0.5	V (min)
V_{RB}	Bottom Reference Voltage		0.3	$V_{RT} - 0.5$	V (max)
				0	V (min)
R_{REF}	Reference Ladder Resistance	V_{RT} to V_{RB}	160	120	Ω (min)
				200	Ω (max)
CLK, PD DIGITAL INPUT CHARACTERISTICS					
V_{IH}	Logical High Input Voltage	$V_{DR} = V_A = 3.6V$		2.0	V (min)
V_{IL}	Logical Low Input Voltage	$V_{DR} = V_A = 2.7V$		0.8	V (max)
I_{IH}	Logical High Input Current	$V_{IH} = V_{DR} = V_A = 3.6V$	10		nA
I_{IL}	Logical Low Input Current	$V_{IL} = 0V$, $V_{DR} = V_A = 2.7V$	-50		nA
C_{IN}	Logic Input Capacitance		3		pF
DIGITAL OUTPUT CHARACTERISTICS					
V_{OH}	High Level Output Voltage	$V_A = V_{DR} = 2.7V$, $I_{OH} = -400$ μA	2.6	2.4	V (min)
V_{OL}	Low Level Output Voltage	$V_A = V_{DR} = 2.7V$, $I_{OL} = 1.0$ mA	0.4	0.5	V (max)

Converter Electrical Characteristics (Continued)

The following specifications apply for $V_A = V_{DR} = +3.0V_{DC}$, $V_{RT} = +1.9V$, $V_{RB} = 0.3V$, $C_L = 5$ pF, $f_{CLK} = 200$ MHz at 50% duty cycle. **Boldface limits apply for $T_A = T_{MIN}$ to T_{MAX}** ; all other limits $T_A = 25^\circ C$ (Notes 7, 8)

Symbol	Parameter	Conditions	Typical (Note 9)	Limits (Note 9)	Units (Limits)
DYNAMIC PERFORMANCE					
ENOB	Effective Number of Bits	$f_{IN} = 4$ MHz, $V_{IN} = FS - 0.25$ dB	7.5		Bits
		$f_{IN} = 20$ MHz, $V_{IN} = FS - 0.25$ dB	7.4		Bits
		$f_{IN} = 50$ MHz, $V_{IN} = FS - 0.25$ dB	7.3	6.9	Bits (min)
		$f_{IN} = 70$ MHz, $V_{IN} = FS - 0.25$ dB	7.2		Bits
		$f_{IN} = 100$ MHz, $V_{IN} = FS - 0.25$ dB	7.0		Bits
SINAD	Signal-to-Noise & Distortion	$f_{IN} = 4$ MHz, $V_{IN} = FS - 0.25$ dB	47		dB
		$f_{IN} = 20$ MHz, $V_{IN} = FS - 0.25$ dB	46		dB
		$f_{IN} = 50$ MHz, $V_{IN} = FS - 0.25$ dB	46	43.3	dB (min)
		$f_{IN} = 70$ MHz, $V_{IN} = FS - 0.25$ dB	45		dB
		$f_{IN} = 100$ MHz, $V_{IN} = FS - 0.25$ dB	44		dB
SNR	Signal-to-Noise Ratio	$f_{IN} = 4$ MHz, $V_{IN} = FS - 0.25$ dB	47		dB
		$f_{IN} = 20$ MHz, $V_{IN} = FS - 0.25$ dB	46		dB
		$f_{IN} = 50$ MHz, $V_{IN} = FS - 0.25$ dB	46	43.4	dB (min)
		$f_{IN} = 70$ MHz, $V_{IN} = FS - 0.25$ dB	45		dB
		$f_{IN} = 100$ MHz, $V_{IN} = FS - 0.25$ dB	44		dB
SFDR	Spurious Free Dynamic Range	$f_{IN} = 4$ MHz, $V_{IN} = FS - 0.25$ dB	60		dBc
		$f_{IN} = 20$ MHz, $V_{IN} = FS - 0.25$ dB	58		dBc
		$f_{IN} = 50$ MHz, $V_{IN} = FS - 0.25$ dB	60		dBc
		$f_{IN} = 70$ MHz, $V_{IN} = FS - 0.25$ dB	57		dBc
		$f_{IN} = 100$ MHz, $V_{IN} = FS - 0.25$ dB	54		dBc
THD	Total Harmonic Distortion	$f_{IN} = 4$ MHz, $V_{IN} = FS - 0.25$ dB	-60		dBc
		$f_{IN} = 20$ MHz, $V_{IN} = FS - 0.25$ dB	-58		dBc
		$f_{IN} = 50$ MHz, $V_{IN} = FS - 0.25$ dB	-60		dBc
		$f_{IN} = 70$ MHz, $V_{IN} = FS - 0.25$ dB	-56		dBc
		$f_{IN} = 100$ MHz, $V_{IN} = FS - 0.25$ dB	-53		dBc
HD2	2nd Harmonic Distortion	$f_{IN} = 4$ MHz, $V_{IN} = FS - 0.25$ dB	-66		dBc
		$f_{IN} = 20$ MHz, $V_{IN} = FS - 0.25$ dB	-68		dBc
		$f_{IN} = 50$ MHz, $V_{IN} = FS - 0.25$ dB	-66		dBc
		$f_{IN} = 70$ MHz, $V_{IN} = FS - 0.25$ dB	-60		dBc
		$f_{IN} = 100$ MHz, $V_{IN} = FS - 0.25$ dB	-55		dBc
HD3	3rd Harmonic Distortion	$f_{IN} = 4$ MHz, $V_{IN} = FS - 0.25$ dB	-72		dBc
		$f_{IN} = 20$ MHz, $V_{IN} = FS - 0.25$ dB	-58		dBc
		$f_{IN} = 50$ MHz, $V_{IN} = FS - 0.25$ dB	-72		dBc
		$f_{IN} = 70$ MHz, $V_{IN} = FS - 0.25$ dB	-58		dBc
		$f_{IN} = 100$ MHz, $V_{IN} = FS - 0.25$ dB	-60		dBc
IMD	Intermodulation Distortion	$f_1 = 11$ MHz, $V_{IN} = FS - 6.25$ dB $f_2 = 12$ MHz, $V_{IN} = FS - 6.25$ dB	-55		dBc
POWER SUPPLY CHARACTERISTICS					
I_A	Analog Supply Current	DC Input	69.75	86	mA (max)
		$f_{IN} = 10$ MHz, $V_{IN} = FS - 3$ dB	69.75		mA (max)
I_{DR}	Output Driver Supply Current	DC Input, PD = Low	0.25	0.6	mA (max)
$I_A + I_{DR}$	Total Operating Current	DC Input, PD = Low	70	86.6	mA (max)
		CLK Low, PD = Hi	0.3		mA
PC	Power Consumption	DC Input, Excluding Reference	210	260	mW (max)
PSRR ₁	Power Supply Rejection Ratio	FSE change with 2.7V to 3.3V change in V_A	54		dB

Converter Electrical Characteristics (Continued)

The following specifications apply for $V_A = V_{DR} = +3.0V_{DC}$, $V_{RT} = +1.9V$, $V_{RB} = 0.3V$, $C_L = 5 \text{ pF}$, $f_{CLK} = 200 \text{ MHz}$ at 50% duty cycle. **Boldface limits apply for $T_A = T_{MIN}$ to T_{MAX}** ; all other limits $T_A = 25^\circ\text{C}$ (Notes 7, 8)

Symbol	Parameter	Conditions	Typical (Note 9)	Limits (Note 9)	Units (Limits)
AC ELECTRICAL CHARACTERISTICS					
f_{C1}	Maximum Conversion Rate		230	200	MHz (min)
f_{C2}	Minimum Conversion Rate		10		MHz
t_{CL}	Minimum Clock Low Time		0.87	1.0	ns (min)
t_{CH}	Minimum Clock High Time		0.65	0.75	ns (min)
t_{OH}	Output Hold Time	CLK to Data Invalid	2.1		ns
t_{OD}	Output Delay	CLK to Data Transition	3.5	2.5	ns (min)
				5	ns (max)
	Pipeline Delay (Latency)		6		Clock Cycles
t_{AD}	Sampling (Aperture) Delay	CLK Rise to Acquisition of Data	2.6		ns
t_{AJ}	Aperture Jitter		2		ps rms

Note 1: Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not guarantee specific performance limits. For guaranteed specifications and test conditions, see the Electrical Characteristics. The guaranteed specifications apply only for the test conditions listed. Some performance characteristics may degrade when the device is not operated under the listed test conditions.

Note 2: All voltages are measured with respect to GND = AGND = DR GND = 0V, unless otherwise specified.

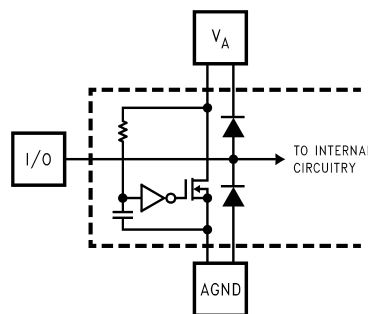
Note 3: When the input voltage at any pin exceeds the power supplies (that is, less than AGND or DR GND, or greater than V_A or V_{DR}), the current at that pin should be limited to 25 mA. The 50 mA maximum package input current rating limits the number of pins that can safely exceed the power supplies with an input current of 25 mA to two.

Note 4: The absolute maximum junction temperature (T_{Jmax}) for this device is 150°C . The maximum allowable power dissipation is dictated by T_{Jmax} , the junction-to-ambient thermal resistance (θ_{JA}), and the ambient temperature (T_A), and can be calculated using the formula $P_{DMAX} = (T_{Jmax} - T_A) / \theta_{JA}$. In the 24-pin TSSOP, θ_{JA} is 92°C/W , so $P_{DMAX} = 1,358 \text{ mW}$ at 25°C and 435 mW at the maximum operating ambient temperature of 85°C . Note that the power consumption of this device under normal operation will typically be about 245 mW (205 mW quiescent power + 16 mW reference ladder power + 24 mW to drive the output bus capacitance). The values for maximum power dissipation listed above will be reached only when the ADC08200 is operated in a severe fault condition (e.g., when input or output pins are driven beyond the power supply voltages, or the power supply polarity is reversed). Obviously, such conditions should always be avoided.

Note 5: Human body model is 100 pF capacitor discharged through a 1.5 k Ω resistor. Machine model is 220 pF discharged through ZERO Ohms.

Note 6: See AN-450, "Surface Mounting Methods and Their Effect on Product Reliability".

Note 7: The analog inputs are protected as shown below. Input voltage magnitudes up to $V_A + 300 \text{ mV}$ or to 300 mV below GND will not damage this device. However, errors in the A/D conversion can occur if the input goes above V_{DR} or below GND by more than 100 mV. For example, if V_A is $2.7V_{DC}$ the full-scale input voltage must be $\leq 2.8V_{DC}$ to ensure accurate conversions.



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Note 8: To guarantee accuracy, it is required that V_A and V_{DR} be well bypassed. Each supply pin must be decoupled with separate bypass capacitors.

Note 9: Typical figures are at $T_J = 25^\circ\text{C}$, and represent most likely parametric norms. Test limits are guaranteed to National's AOQL (Average Outgoing Quality Level).

Specification Definitions

APERTURE (SAMPLING) DELAY is that time required after the rise of the clock input for the sampling switch to open. The Sample/Hold circuit effectively stops capturing the input signal and goes into the “hold” mode t_{AD} after the clock goes high.

APERTURE JITTER is the variation in aperture delay from sample to sample. Aperture jitter shows up as input noise.

CLOCK DUTY CYCLE is the ratio of the time that the clock wave form is at a logic high to the total time of one clock period.

DIFFERENTIAL NON-LINEARITY (DNL) is the measure of the maximum deviation from the ideal step size of 1 LSB. Measured at 200 MSPS with a ramp input.

EFFECTIVE NUMBER OF BITS (ENOB, or EFFECTIVE BITS) is another method of specifying Signal-to-Noise and Distortion Ratio, or SINAD. ENOB is defined as $(\text{SINAD} - 1.76) / 6.02$ and says that the converter is equivalent to a perfect ADC of this (ENOB) number of bits.

FULL POWER BANDWIDTH is a measure of the frequency at which the reconstructed output fundamental drops 3 dB below its low frequency value for a full scale input.

FULL-SCALE ERROR is a measure of how far the last code transition is from the ideal $1\frac{1}{2}$ LSB below V_{RT} and is defined as:

$$V_{\max} + 1.5 \text{ LSB} - V_{RT}$$

where V_{\max} is the voltage at which the transition to the maximum (full scale) code occurs.

INTEGRAL NON-LINEARITY (INL) is a measure of the deviation of each individual code from a line drawn from zero scale ($\frac{1}{2}$ LSB below the first code transition) through positive full scale ($\frac{1}{2}$ LSB above the last code transition). The deviation of any given code from this straight line is measured from the center of that code value. The end point test method is used. Measured at 200 MSPS with a ramp input.

INTERMODULATION DISTORTION (IMD) is the creation of additional spectral components as a result of two sinusoidal frequencies being applied to the ADC input at the same time. It is defined as the ratio of the power in the second and third order intermodulation products to the power in one of the original frequencies. IMD is usually expressed in dBFS.

MISSING CODES are those output codes that are skipped and will never appear at the ADC outputs. These codes cannot be reached with any input value.

OUTPUT DELAY is the time delay after the rising edge of the input clock before the data update is present at the output pins.

OUTPUT HOLD TIME is the length of time that the output data is valid after the rise of the input clock.

PIPELINE DELAY (LATENCY) is the number of clock cycles between initiation of conversion and when that data is presented to the output driver stage. New data is available at every clock cycle, but the data lags the conversion by the Pipeline Delay plus the Output Delay.

POWER SUPPLY REJECTION RATIO (PSRR) is a measure of how well the ADC rejects a change in the power supply voltage. For the ADC08200, PSRR1 is the ratio of the change in Full-Scale Error that results from a change in the dc power supply voltage, expressed in dB. PSRR2 is a measure of how well an a.c. signal riding upon the power supply is rejected from the output.

SIGNAL TO NOISE RATIO (SNR) is the ratio, expressed in dB, of the rms value of the input signal at the output to the rms value of the sum of all other spectral components below one-half the sampling frequency, not including harmonics or dc.

SIGNAL TO NOISE PLUS DISTORTION (S/(N+D) or SINAD) is the ratio, expressed in dB, of the rms value of the input signal at the output to the rms value of all of the other spectral components below half the clock frequency, including harmonics but excluding dc.

SPURIOUS FREE DYNAMIC RANGE (SFDR) is the difference, expressed in dB, between the rms values of the input signal at the output and the peak spurious signal, where a spurious signal is any signal present in the output spectrum that is not present at the input.

TOTAL HARMONIC DISTORTION (THD) is the ratio expressed in dB, of the rms total of the first nine harmonic levels at the output to the level of the fundamental at the output. THD is calculated as

$$\text{THD} = 20 \times \log \sqrt{\frac{f_2^2 + f_3^2 + f_4^2 + f_5^2 + f_6^2 + f_7^2 + f_8^2 + f_9^2 + f_{10}^2}{f_1^2}}$$

where f_1 is the RMS power of the fundamental (output) frequency and f_2 through f_{10} are the RMS power of the first 9 harmonic frequencies in the output spectrum

ZERO SCALE OFFSET ERROR is the error in the input voltage required to cause the first code transition. It is defined as

$$V_{\text{OFF}} = V_{\text{ZT}} - V_{\text{RB}}$$

where V_{ZT} is the first code transition input voltage.

Timing Diagram

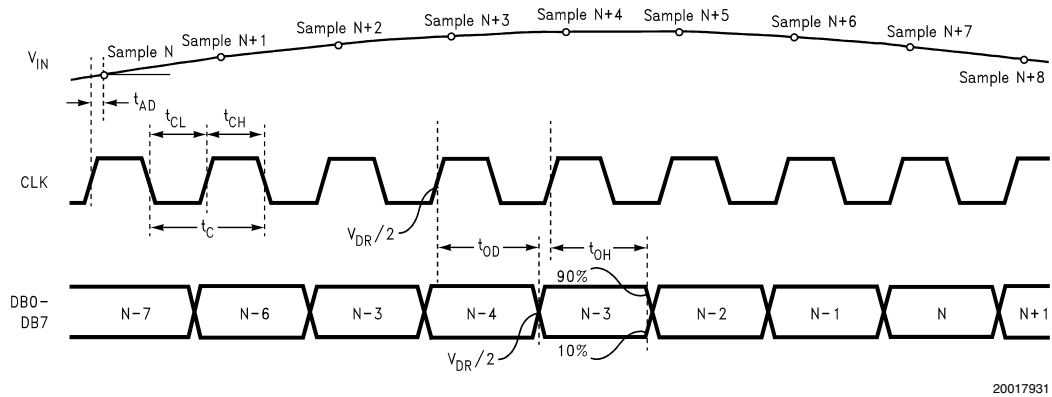
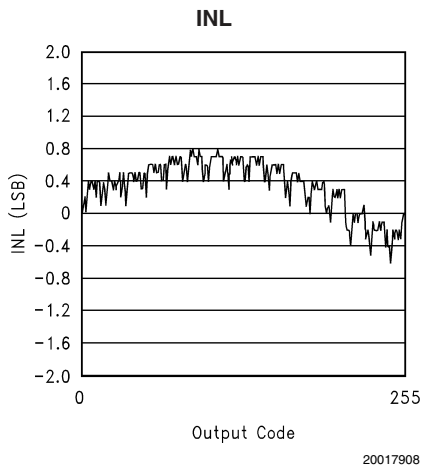
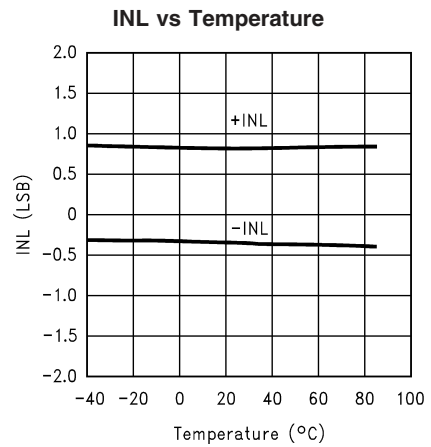


FIGURE 1. ADC08200 Timing Diagram

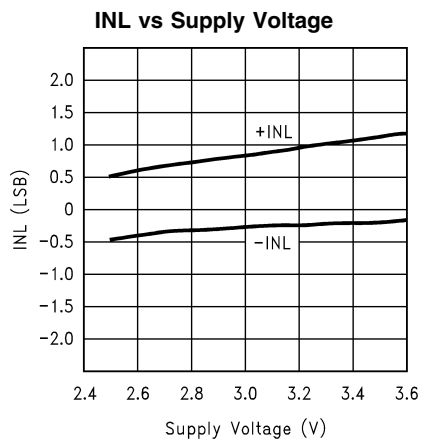
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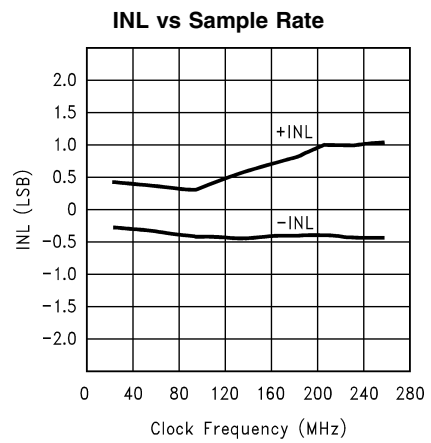
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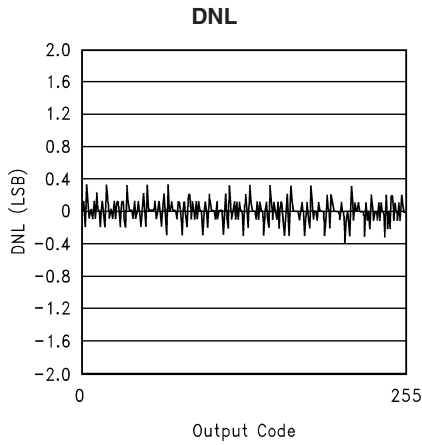


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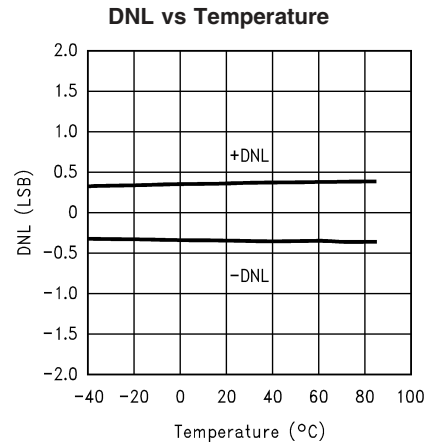


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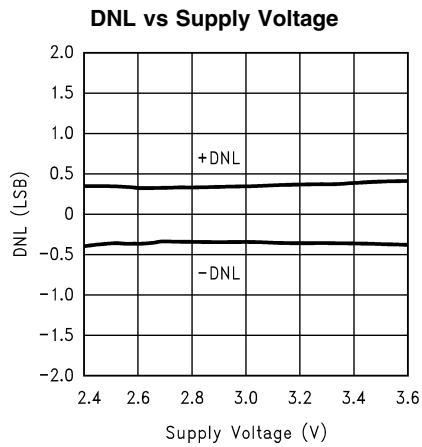
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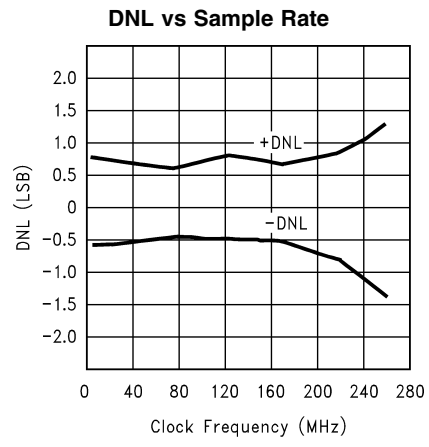
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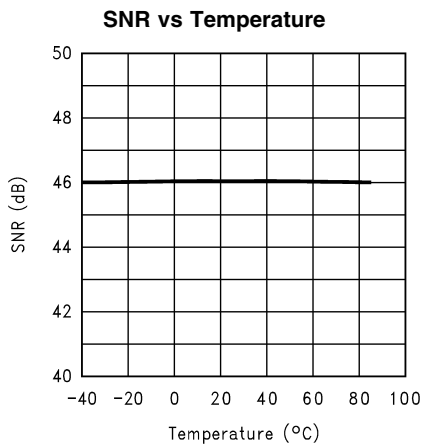
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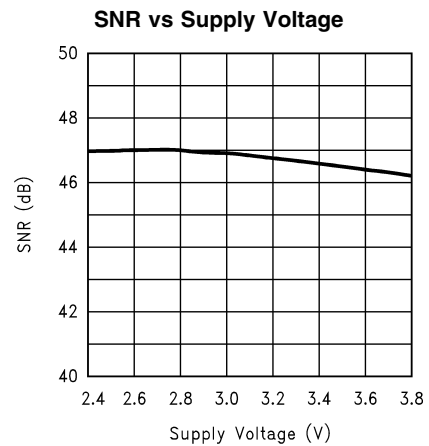
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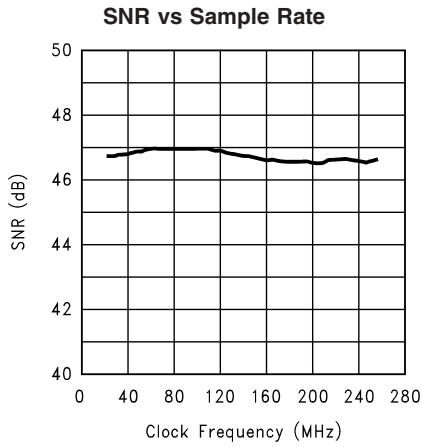


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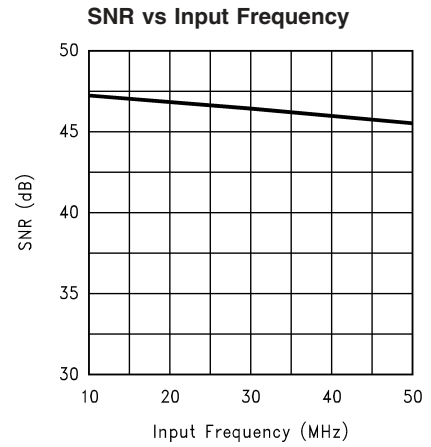


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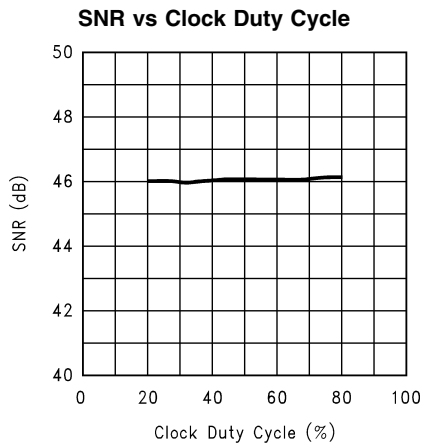
Typical Performance Characteristics $V_A = V_{DR} = 3V$, $f_{CLK} = 200\text{ MHz}$, $f_{IN} = 50\text{ MHz}$, unless otherwise stated (Continued)



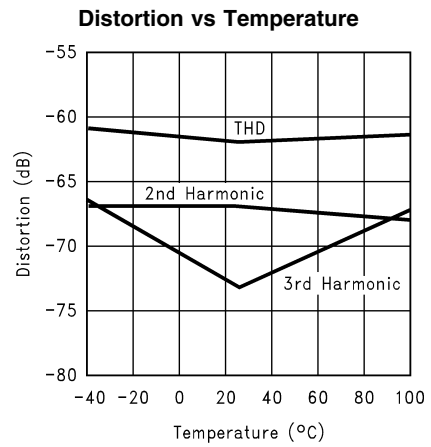
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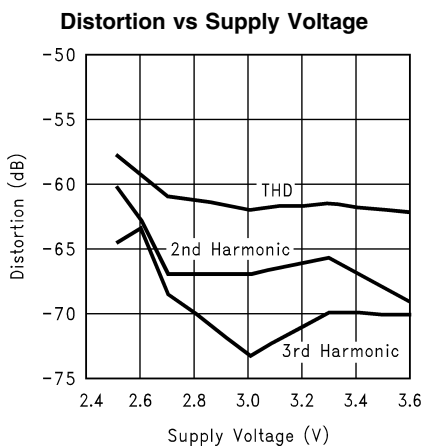
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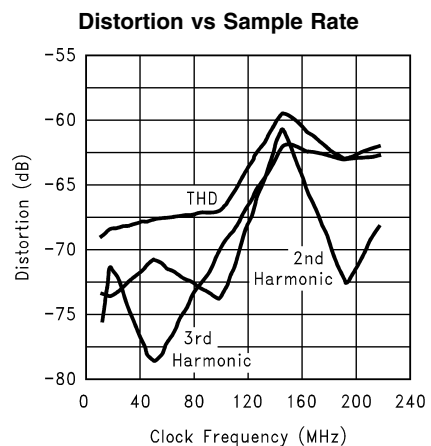
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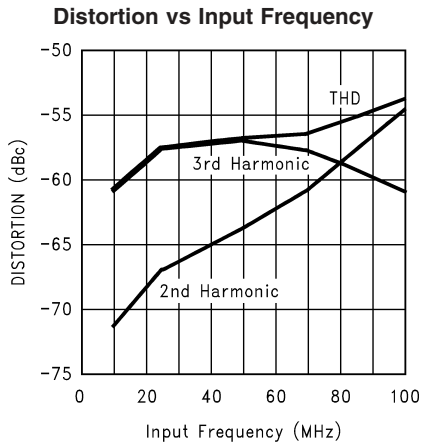


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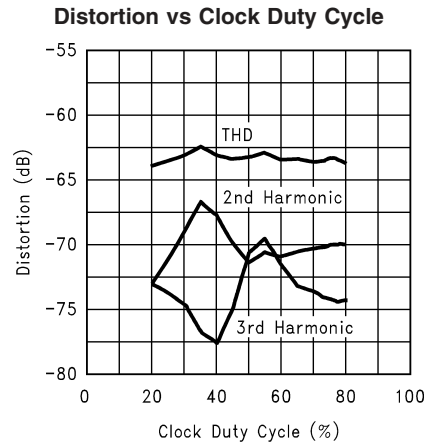


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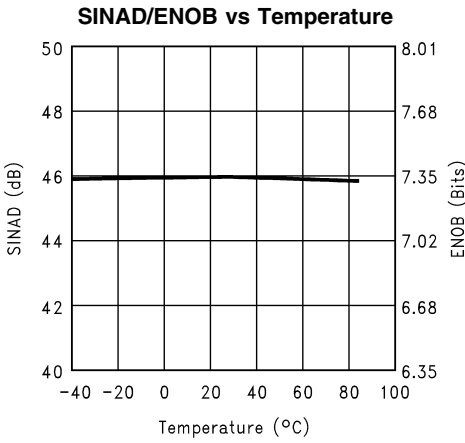
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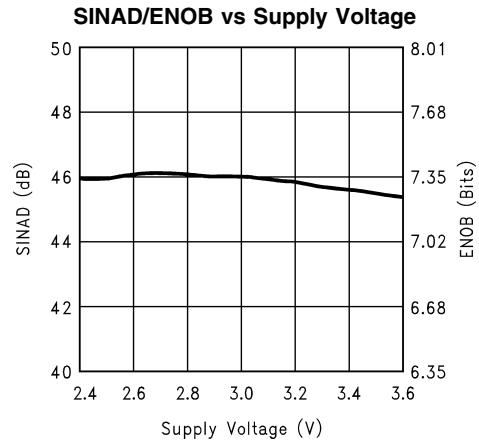
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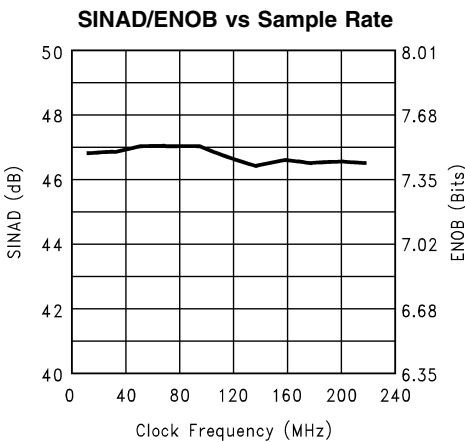
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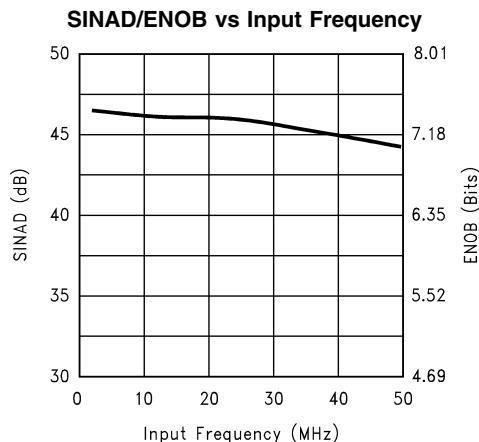
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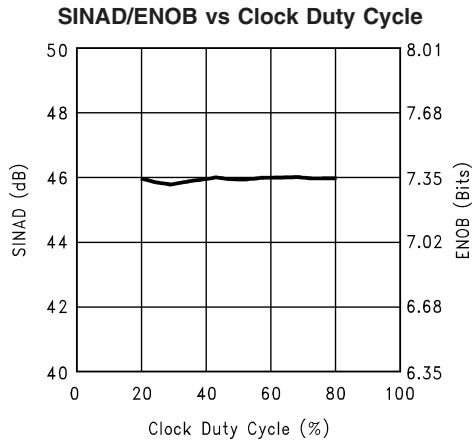


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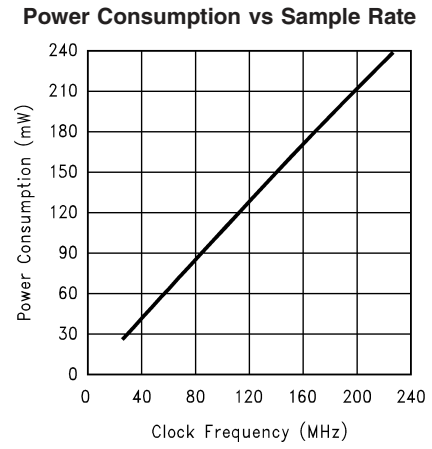


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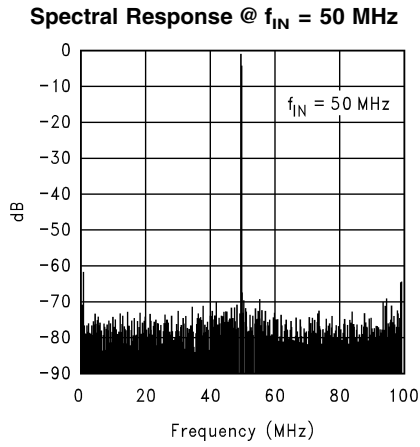
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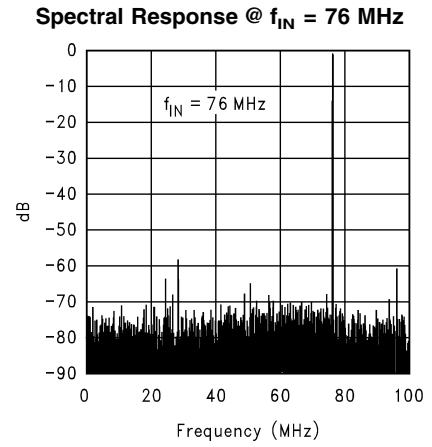
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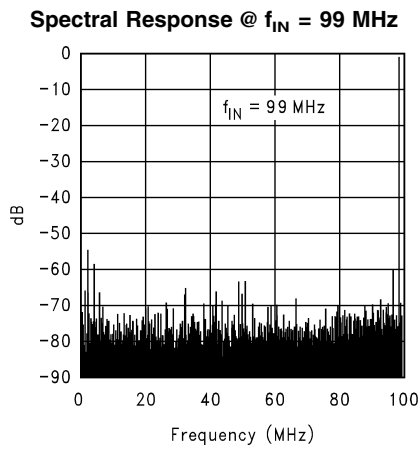
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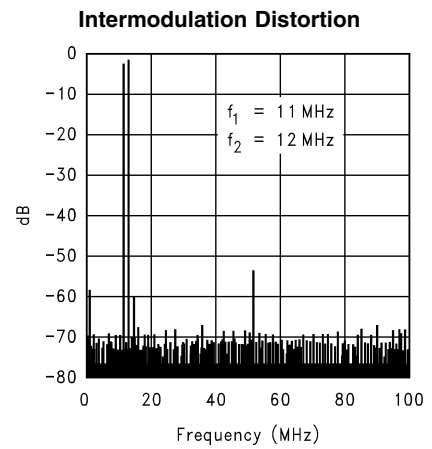
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Functional Description

The ADC08200 uses a new, unique architecture that achieves over 7 effective bits at input frequencies up to and beyond 100 MHz.

The analog input signal that is within the voltage range set by V_{RT} and V_{RB} is digitized to eight bits. Input voltages below V_{RB} will cause the output word to consist of all zeroes. Input voltages above V_{RT} will cause the output word to consist of all ones.

Incorporating a switched capacitor bandgap, the ADC08200 exhibits a power consumption that is proportional to frequency, limiting power consumption to what is needed at the clock rate that is used. This and its excellent performance over a wide range of clock frequencies makes it an ideal choice as a single ADC for many 8-bit needs.

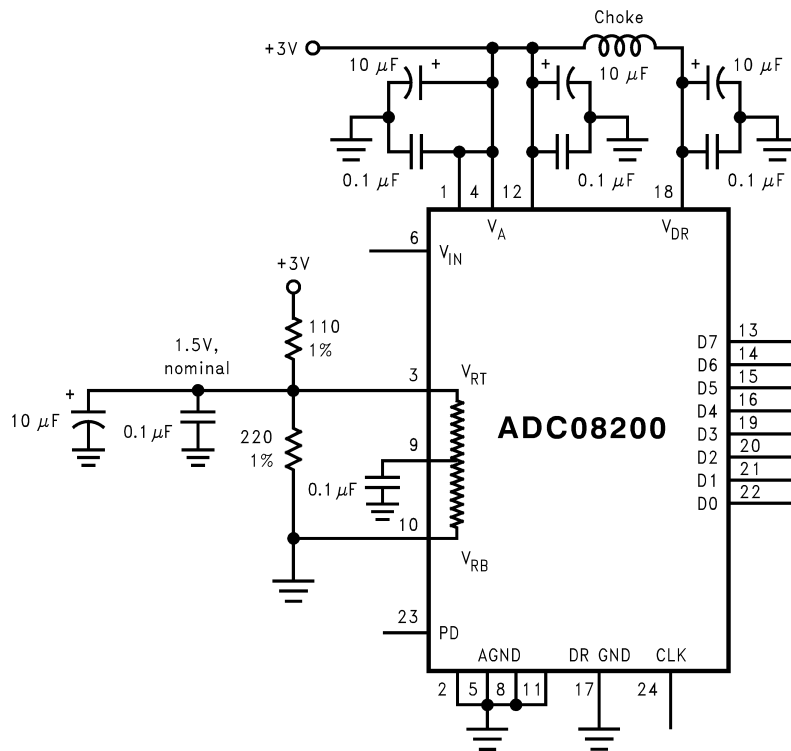
Data is acquired at the rising edge of the clock and the digital equivalent of that data is available at the digital outputs 6 clock cycles plus t_{OD} later. The ADC08200 will convert as

long as the clock signal is present. The device is in the active state when the Power Down pin (PD) is low. When the PD pin is high, the device is in the power down mode, where the output pins hold the last conversion before the PD pin went high and the device consumes just 1 mW.

Applications Information

1.0 REFERENCE INPUTS

The reference inputs V_{RT} and V_{RB} are the top and bottom of the reference ladder, respectively. Input signals between these two voltages will be digitized to 8 bits. External voltages applied to the reference input pins should be within the range specified in the Operating Ratings table (0.5V to $(V_A - 0.3V)$ for V_{RT} and -100 mV to $(V_{RT} - 0.5V)$ for V_{RB}). Any device used to drive the reference pins should be able to source sufficient current into the V_{RT} pin and sink sufficient current from the V_{RB} pin.



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FIGURE 2. Simple, low component count reference biasing. Because of the ladder and external resistor tolerances, the reference voltage can vary too much for some applications.

The reference bias circuit of *Figure 2* is very simple and the performance is adequate for many applications. However, circuit tolerances will lead to a wide reference voltage range. Better reference stability can be achieved by driving the reference pins with low impedance sources.

The circuit of *Figure 3* will allow a more accurate setting of the reference voltages. The lower amplifier must have bipolar supplies as its output voltage must go negative to force V_{RB} to any voltage below the V_{BE} of the PNP transistor. Of course, the divider resistors at the amplifier input could be changed to suit your reference voltage needs, or the divider can be replaced with potentiometers for precise settings.

The bottom of the ladder (V_{RB}) may simply be returned to ground if the minimum input signal excursion is 0V. Be sure that the driving source can source sufficient current into the V_{RT} pin and sink enough current from the V_{RB} pin to keep these pins stable.

The LMC662 amplifier shown was chosen for its low offset voltage and low cost.

V_{RT} should always be at least 0.5V more positive than V_{RB} to minimize noise.

The V_{RM} pin is the center of the reference ladder and should be bypassed to a quiet point in the analog ground plane with a 0.1 μ F capacitor. DO NOT allow this pin to float.

Applications Information (Continued)

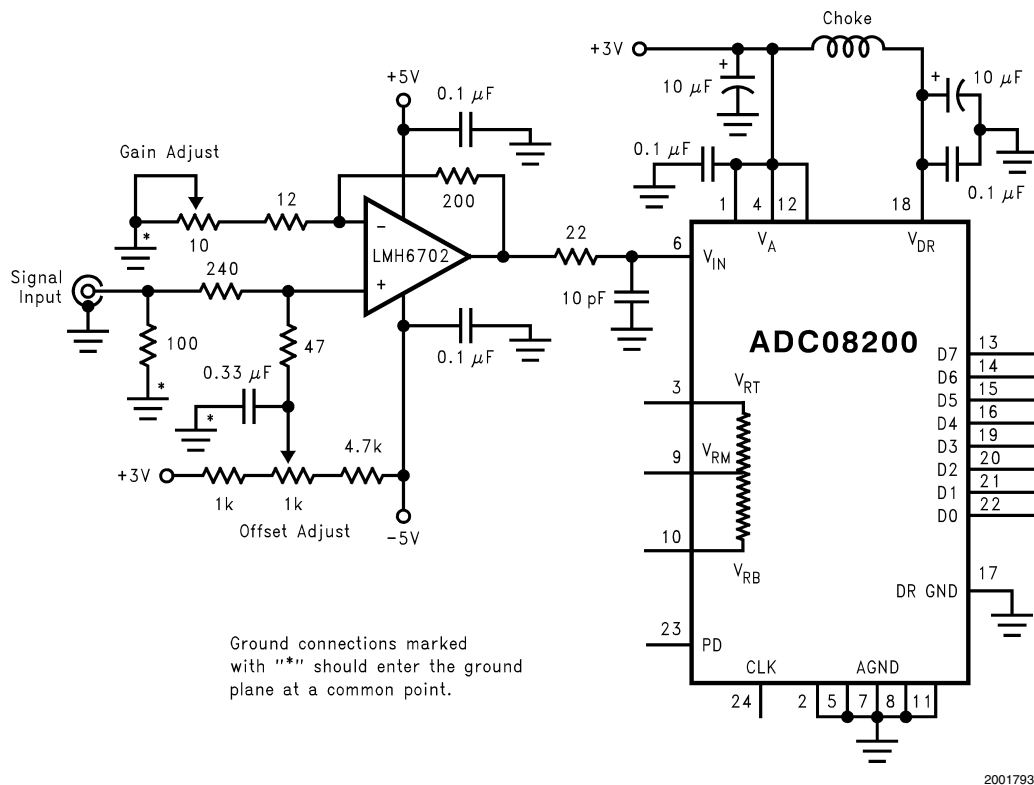


FIGURE 4. The input amplifier should incorporate some gain for best performance (see text).

3.0 POWER SUPPLY CONSIDERATIONS

A/D converters draw sufficient transient current to corrupt their own power supplies if not adequately bypassed. A 10 μF tantalum or aluminum electrolytic capacitor should be placed within an inch (2.5 cm) of the A/D power pins, with a 0.1 μF ceramic chip capacitor placed within one centimeter of the converter's power supply pins. Leadless chip capacitors are preferred because they have low lead inductance.

While a single voltage source is recommended for the V_A and V_{DR} supplies of the ADC08200, these supply pins should be well isolated from each other to prevent any digital noise from being coupled into the analog portions of the ADC. A choke or 27 Ω resistor is recommended between these supply lines with adequate bypass capacitors close to the supply pins.

As is the case with all high speed converters, the ADC08200 should be assumed to have little power supply rejection. None of the supplies for the converter should be the supply that is used for other digital circuitry in any system with a lot of digital power being consumed. The ADC supplies should be the same supply used for other analog circuitry.

No pin should ever have a voltage on it that is in excess of the supply voltage or below ground by more than 300 mV, not even on a transient basis. This can be a problem upon application of power and power shut-down. Be sure that the supplies to circuits driving any of the input pins, analog or digital, do not come up any faster than does the voltage at the ADC08200 power pins.

4.0 THE DIGITAL INPUT PINS

The ADC08200 has two digital input pins: The PD pin and the Clock pin.

4.1 The PD Pin

The Power Down (PD) pin, when high, puts the ADC08200 into a low power mode where power consumption is reduced to 1 mW. Output data is valid and accurate about 1 millisecond after the PD pin is brought low.

The digital output pins retain the last conversion output code when either the clock is stopped or the PD pin is high.

4.2 The ADC08200 Clock

Although the ADC08200 is tested and its performance is guaranteed with a 200 MHz clock, it typically will function well with clock frequencies from 10 MHz to 230 MHz.

The low and high times of the clock signal can affect the performance of any A/D Converter. Because achieving a precise duty cycle is difficult, the ADC08200 is designed to maintain performance over a range of duty cycles. While it is specified and performance is guaranteed with a 50% clock duty cycle and 200 Msps, ADC08200 performance is typically maintained with clock high and low times of 0.65 ns and 0.87 ns, respectively, corresponding to a clock duty cycle range of 13% to 82.5% with a 200 MHz clock.

The **CLOCK** line should be series terminated at the clock source in the characteristic impedance of that line. If the clock line is longer than

Applications Information (Continued)

$$\frac{t_r}{6 \times t_{prop}}$$

where t_r is the clock rise time and t_{prop} is the propagation rate of the signal along the trace, the **CLOCK** pin should be a.c. terminated with a series RC to ground such that the resistor value is equal to the characteristic impedance of the clock line and the capacitor value is

$$C \geq \frac{4 \times t_{prop} \times L}{Z_0}$$

where "L" is the line length in inches, t_{prop} is the signal propagation rate down the clock line and Z_0 is the characteristic impedance of the clock line. Typical t_{prop} is about 150 ps/inch on FR-4 board material. For FR-4 board material, the value of C becomes

$$C \geq \frac{6 \times 10^{-10} \times L}{Z_0}$$

Where L is the length of the clock line in inches.

This termination should be located as close as possible to, but within one centimeter of, the ADC08200 clock pin.

5.0 LAYOUT AND GROUNDING

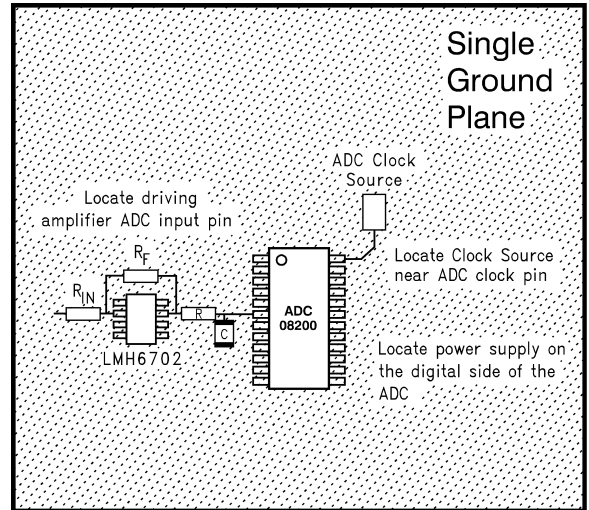
Proper grounding and proper routing of all signals are essential to ensure accurate conversion. A combined analog and digital ground plane should be used.

Since digital switching transients are composed largely of high frequency components, total ground plane copper weight will have little effect upon the logic-generated noise because of the skin effect. Total surface area is more important than is total ground plane volume. Capacitive coupling between the typically noisy digital circuitry and the sensitive analog circuitry can lead to poor performance that may seem impossible to isolate and remedy. The solution is to keep the analog circuitry well separated from the digital circuitry.

High power digital components should not be located on or near a straight line between the ADC or any linear component and the power supply area as the resulting common return current path could cause fluctuation in the analog input "ground" return of the ADC.

Generally, analog and digital lines should cross each other at 90° to avoid getting digital noise into the analog path. In high frequency systems, however, avoid crossing analog and digital lines altogether. Clock lines should be isolated from ALL other lines, analog AND digital. Even the generally accepted 90° crossing should be avoided as even a little coupling can cause problems at high frequencies. Best performance at high frequencies is obtained with a straight signal path.

The analog input should be isolated from noisy signal traces to avoid coupling of spurious signals into the input. Any external component (e.g., a filter capacitor) connected between the converter's input and ground should be connected to a very clean point in the analog ground plane.



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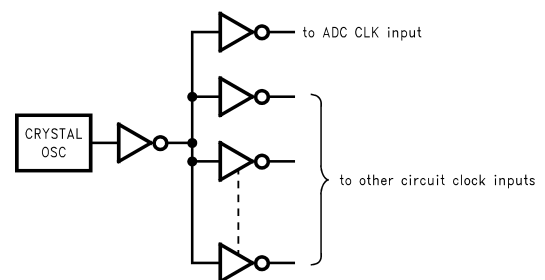
FIGURE 5. Layout Example

Figure 5 gives an example of a suitable layout. All analog circuitry (input amplifiers, filters, reference components, etc.) should be placed together away from any digital components.

6.0 DYNAMIC PERFORMANCE

The ADC08200 is ac tested and its dynamic performance is guaranteed. To meet the published specifications, the clock source driving the CLK input must exhibit less than 2 ps (rms) of jitter. For best ac performance, isolating the ADC clock from any digital circuitry should be done with adequate buffers, as with a clock tree. See Figure 6.

It is good practice to keep the ADC clock line as short as possible and to keep it well away from any other signals. Other signals can introduce jitter into the clock signal. The clock signal can also introduce noise into the analog path.



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FIGURE 6. Isolating the ADC Clock from Digital Circuitry

7.0 COMMON APPLICATION PITFALLS

Driving the inputs (analog or digital) beyond the power supply rails. For proper operation, all inputs should not go more than 300 mV below the ground pins or 300 mV above the supply pins. Exceeding these limits on even a transient basis may cause faulty or erratic operation. It is not uncommon for high speed digital circuits (e.g., 74F and 74AC

Applications Information (Continued)

devices) to exhibit undershoot that goes more than a volt below ground. A 51 Ω resistor in series with the offending digital input will usually eliminate the problem.

Care should be taken not to overdrive the inputs of the ADC08200. Such practice may lead to conversion inaccuracies and even to device damage.

Attempting to drive a high capacitance digital data bus.

The more capacitance the output drivers must charge for each conversion, the more instantaneous digital current is required from V_{DR} and DR GND. These large charging current spikes can couple into the analog section, degrading dynamic performance. Buffering the digital data outputs (with a 74AF541, for example) may be necessary if the data bus capacitance exceeds 5 pF. Dynamic performance can also be improved by adding 33 Ω to 47 Ω series resistors at each digital output, reducing the energy coupled back into the converter input pins.

Using an inadequate amplifier to drive the analog input.

As explained in Section 2.0, the capacitance seen at the

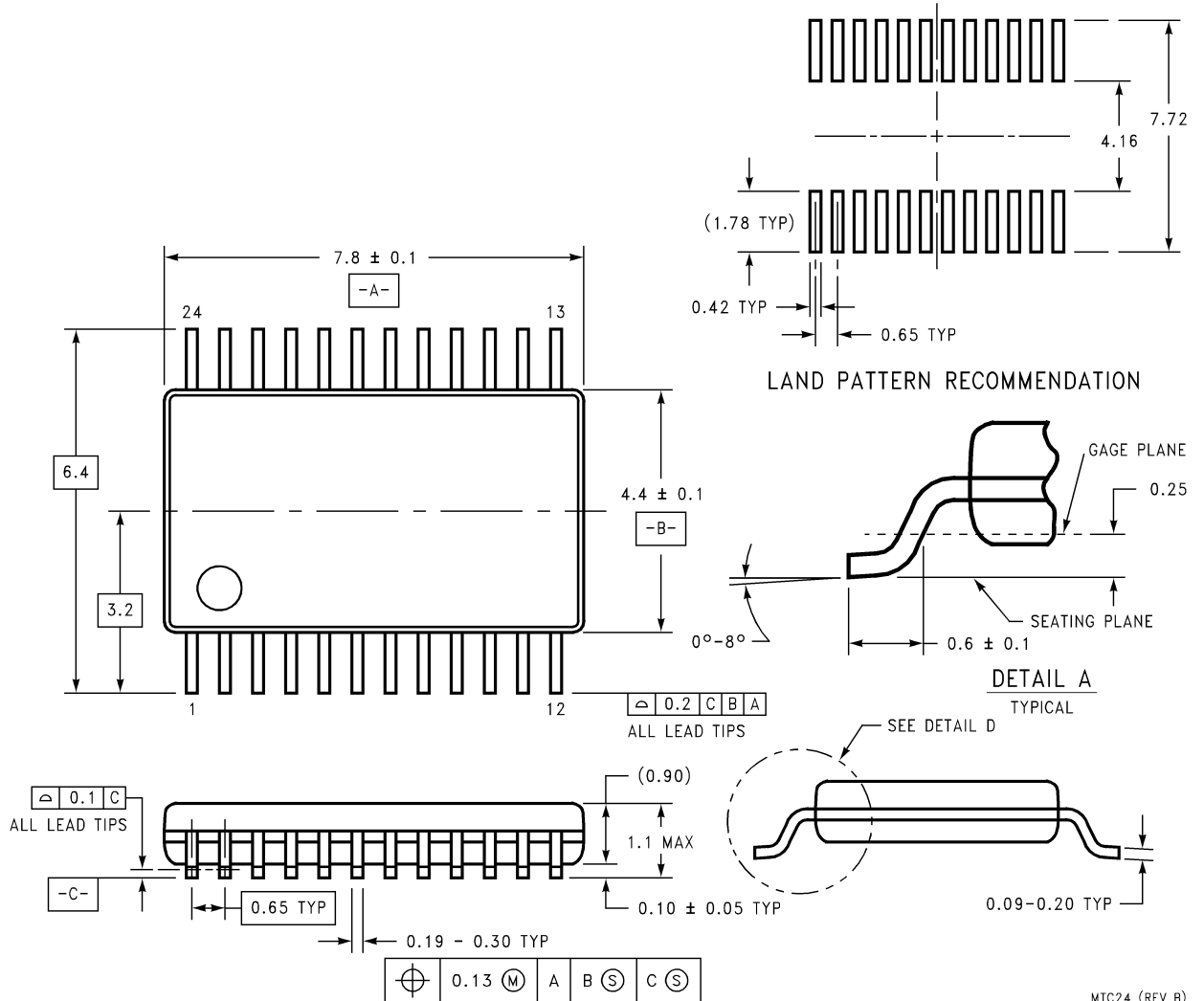
input alternates between 3 pF and 4 pF with the clock. This dynamic capacitance is more difficult to drive than is a fixed capacitance, and should be considered when choosing a driving device.

Driving the V_{RT} pin or the V_{RB} pin with devices that can not source or sink the current required by the ladder.

As mentioned in Section 1.0, care should be taken to see that any driving devices can source sufficient current into the V_{RT} pin and sink sufficient current from the V_{RB} pin. If these pins are not driven with devices that can handle the required current, these reference pins will not be stable, resulting in a reduction of dynamic performance.

Using a clock source with excessive jitter, using an excessively long clock signal trace, or having other signals coupled to the clock signal trace. This will cause the sampling interval to vary, causing excessive output noise and a reduction in SNR performance. The use of simple gates with RC timing is generally inadequate as a clock source.

Physical Dimensions inches (millimeters)
unless otherwise noted



NOTES: UNLESS OTHERWISE SPECIFIED
REFERENCE JEDEC REGISTRATION mo-153, VARIATION AD, DATED 7/93.

24-Lead Package TC
Order Number ADC08200C1MT
NS Package Number MTC24

MTC24 (REV B)

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